

DOSEMI**IGBT****DG50H12T2****1200V/50A IGBT with Diode****General Description**

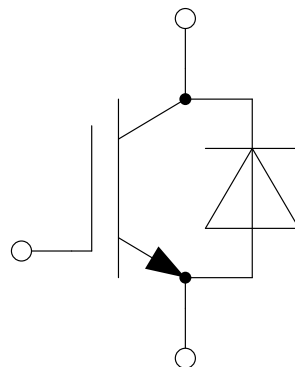
DOSEMI IGBT Power Discrete provides ultra low conduction loss as well as low switching loss. They are designed for the applications such as general inverters and UPS.

Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching loss
- Maximum junction temperature 175°C
- $V_{CE(sat)}$ with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Equivalent Circuit Schematic

Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage Transient Gate-Emitter Voltage	± 20 -25/+30	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	100 50	A
I_{CM}	Pulsed Collector Current t_p limited by T_{vjmax}	150	A
P_D	Maximum Power Dissipation @ $T_{vj}=175^{\circ}\text{C}$	672	W

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	91 50	A
I_{FM}	Diode Maximum Forward Current t_p limited by T_{vjmax}	150	A

Discrete

Symbol	Description	Values	Unit
T_{vjop}	Operating Junction Temperature	-40 to +175	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
T_S	Soldering Temperature, 1.6mm from case for 10s	260	$^{\circ}\text{C}$

IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=50\text{A}, V_{GE}=15\text{V}, T_{vj}=25^{\circ}\text{C}$		1.90	2.35	V
		$I_C=50\text{A}, V_{GE}=15\text{V}, T_{vj}=150^{\circ}\text{C}$		2.65		
		$I_C=50\text{A}, V_{GE}=15\text{V}, T_{vj}=175^{\circ}\text{C}$		2.80		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=2.00\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$	5.0	5.8	6.5	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			200	μA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			100	nA
R_{Gint}	Internal Gate Resistance			0		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		8.69		nF
C_{oes}	Output Capacitance			0.29		nF
C_{res}	Reverse Transfer Capacitance			0.14		nF
Q_G	Gate Charge	$V_{GE}=-8\dots+15\text{V}$		0.58		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=50\text{A}, R_G=10\Omega, V_{GE}=-10/+15\text{V}, L_S=40\text{nH}, T_{vj}=25^{\circ}\text{C}$		46		ns
t_r	Rise Time			76		ns
$t_{d(off)}$	Turn-Off Delay Time			129		ns
t_f	Fall Time			131		ns
E_{on}	Turn-On Switching Loss			5.6		mJ
E_{off}	Turn-Off Switching Loss			1.5		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=50\text{A}, R_G=10\Omega, V_{GE}=-10/+15\text{V}, L_S=40\text{nH}, T_{vj}=150^{\circ}\text{C}$		48		ns
t_r	Rise Time			79		ns
$t_{d(off)}$	Turn-Off Delay Time			171		ns
t_f	Fall Time			171		ns
E_{on}	Turn-On Switching Loss			6.8		mJ
E_{off}	Turn-Off Switching Loss			2.1		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=50\text{A}, R_G=10\Omega, V_{GE}=-10/+15\text{V}, L_S=40\text{nH}, T_{vj}=175^{\circ}\text{C}$		54		ns
t_r	Rise Time			80		ns
$t_{d(off)}$	Turn-Off Delay Time			175		ns
t_f	Fall Time			180		ns
E_{on}	Turn-On Switching Loss			7.2		mJ
E_{off}	Turn-Off Switching Loss			2.3		mJ

Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=50\text{A}, V_{GE}=0\text{V}, T_{vj}=25^\circ\text{C}$		2.00	2.45	V
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_{vj}=150^\circ\text{C}$		2.00		
		$I_F=50\text{A}, V_{GE}=0\text{V}, T_{vj}=175^\circ\text{C}$		2.00		
t_{rr}	Diode Reverse Recovery Time	$V_R=600\text{V}, I_F=50\text{A},$ $-di/dt=460\text{A}/\mu\text{s}, V_{GE}=-10\text{V}$ $L_S=40\text{nH}, T_{vj}=25^\circ\text{C}$		192		ns
Q_r	Recovered Charge			5.1		μC
I_{RM}	Peak Reverse Recovery Current			27		A
E_{rec}	Reverse Recovery Energy			1.8		mJ
t_{rr}	Diode Reverse Recovery Time	$V_R=600\text{V}, I_F=50\text{A},$ $-di/dt=490\text{A}/\mu\text{s}, V_{GE}=-10\text{V}$ $L_S=40\text{nH}, T_{vj}=150^\circ\text{C}$		351		ns
Q_r	Recovered Charge			9.3		μC
I_{RM}	Peak Reverse Recovery Current			38		A
E_{rec}	Reverse Recovery Energy			3.7		mJ
t_{rr}	Diode Reverse Recovery Time	$V_R=600\text{V}, I_F=50\text{A},$ $-di/dt=500\text{A}/\mu\text{s}, V_{GE}=-10\text{V}$ $L_S=40\text{nH}, T_{vj}=175^\circ\text{C}$		388		ns
Q_r	Recovered Charge			10.9		μC
I_{RM}	Peak Reverse Recovery Current			40		A
E_{rec}	Reverse Recovery Energy			4.5		mJ

Discrete Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per IGBT)			0.223	K/W
	Junction-to-Case (per Diode)			0.523	
R_{thJA}	Junction-to-Ambient		40		K/W

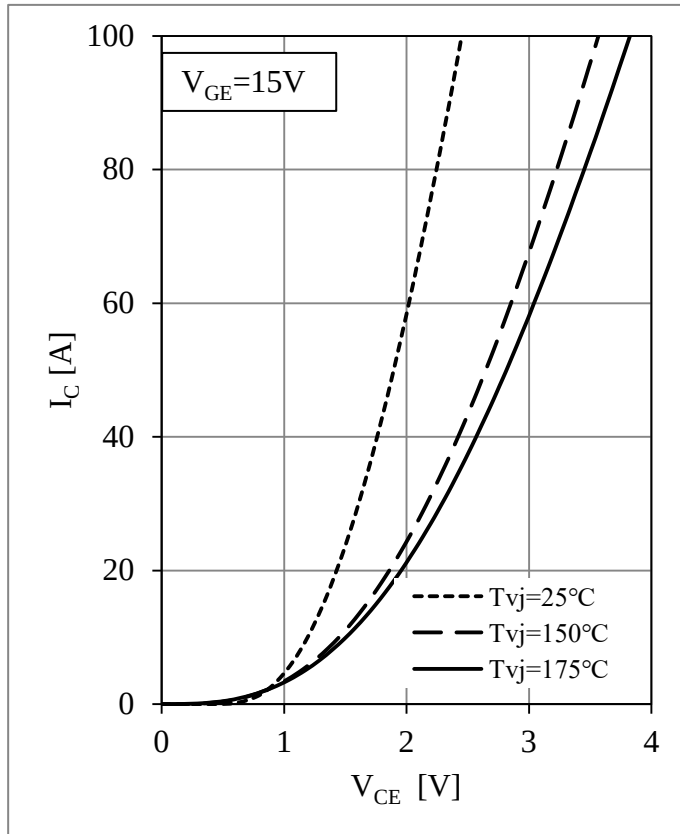


Fig 1. IGBT-inverter Output Characteristics

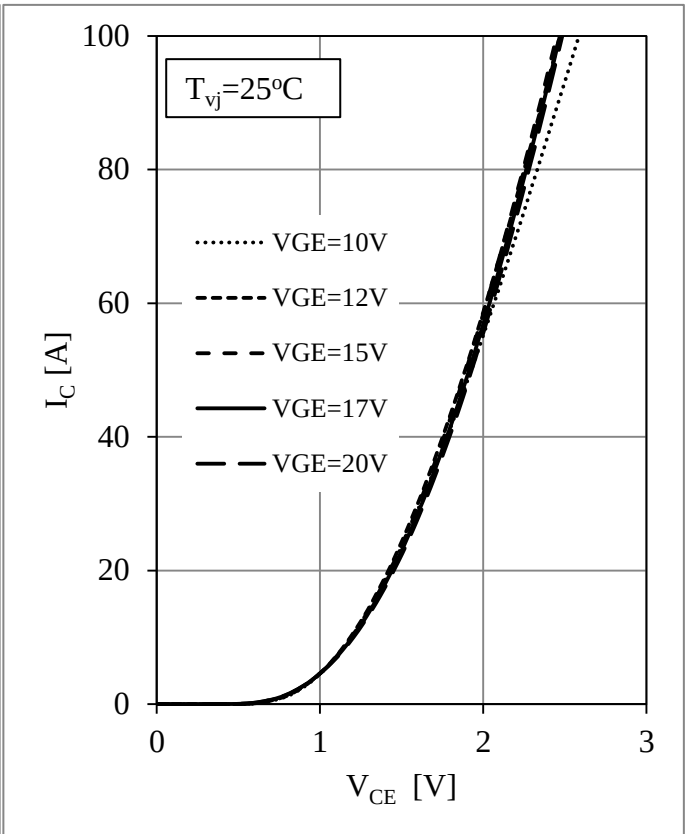


Fig 2. IGBT Output Characteristics

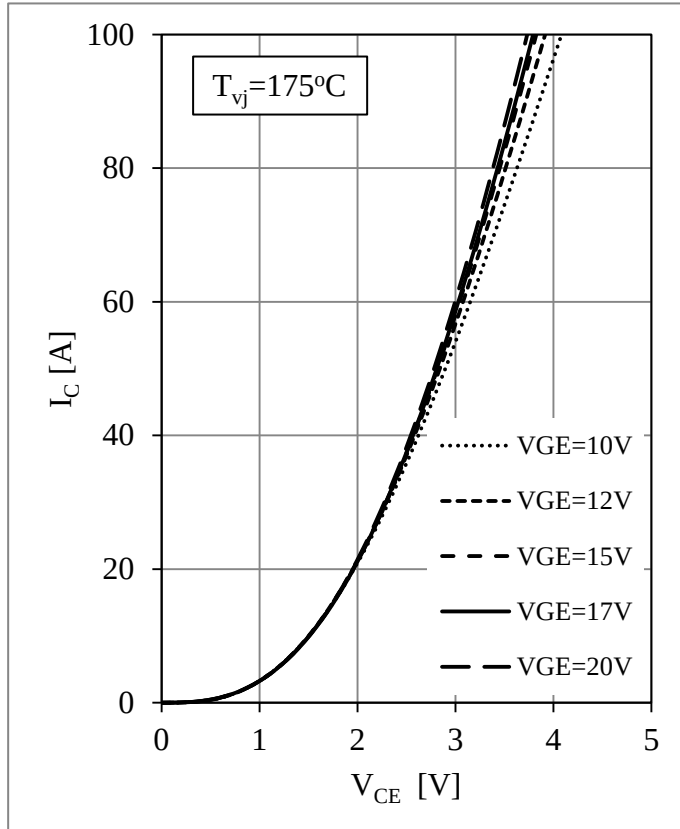


Fig 3. IGBT Output Characterist

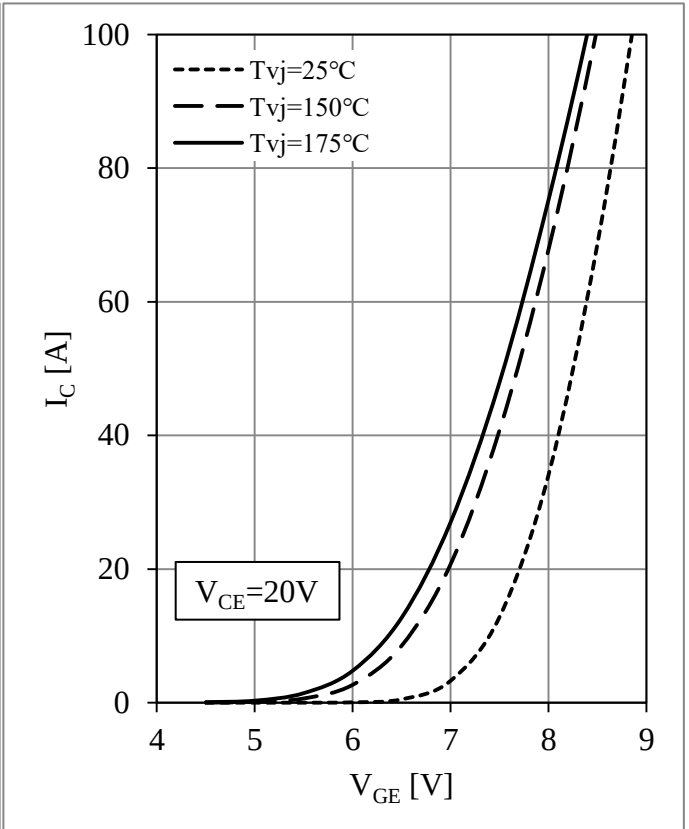
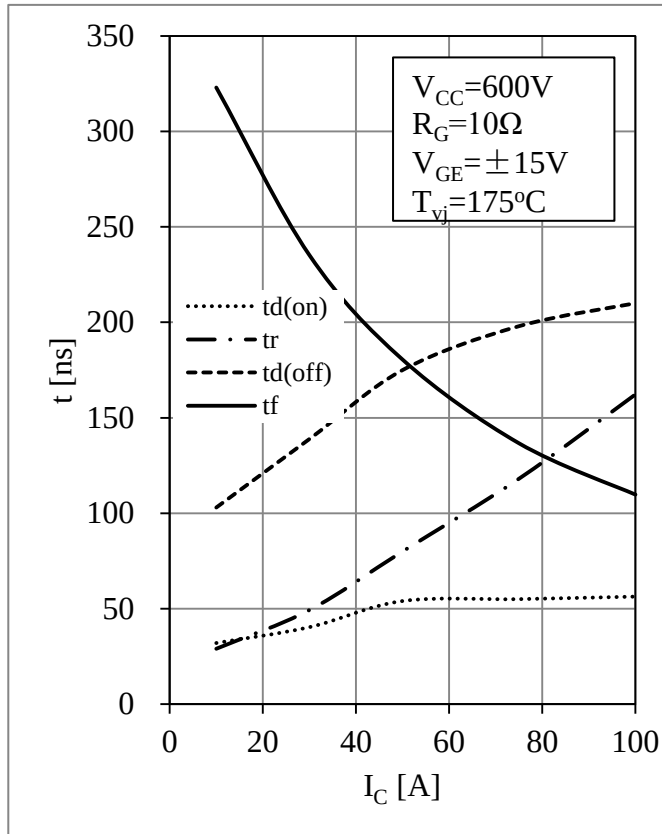
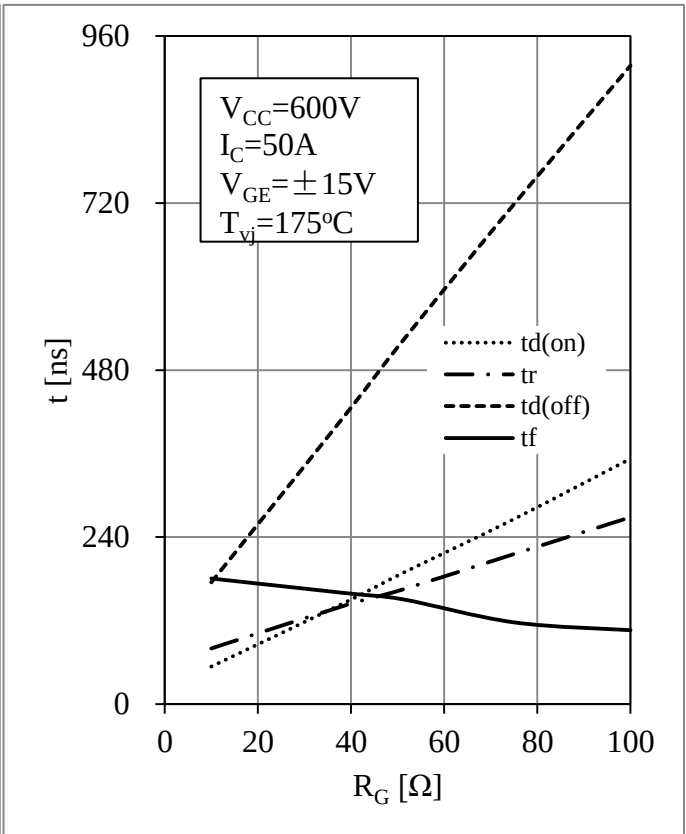
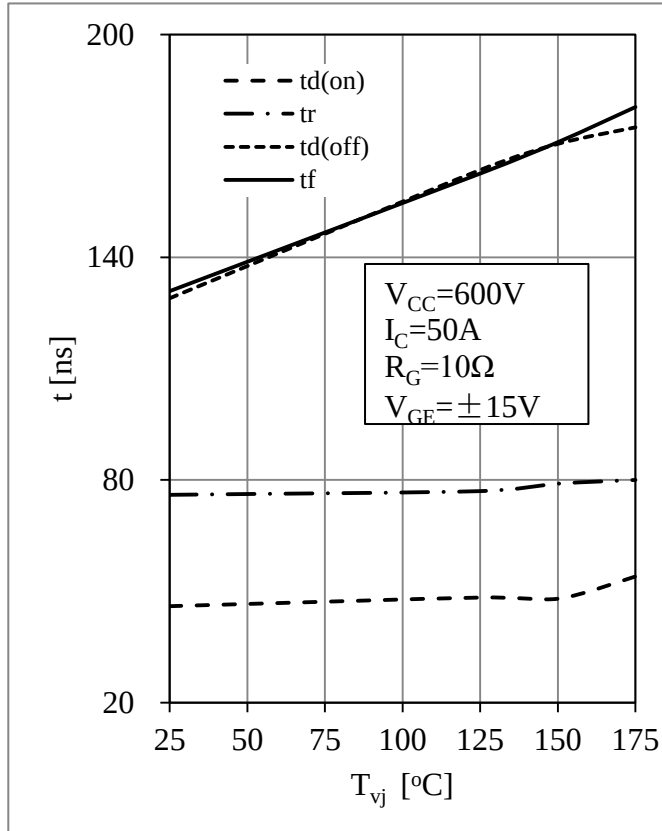
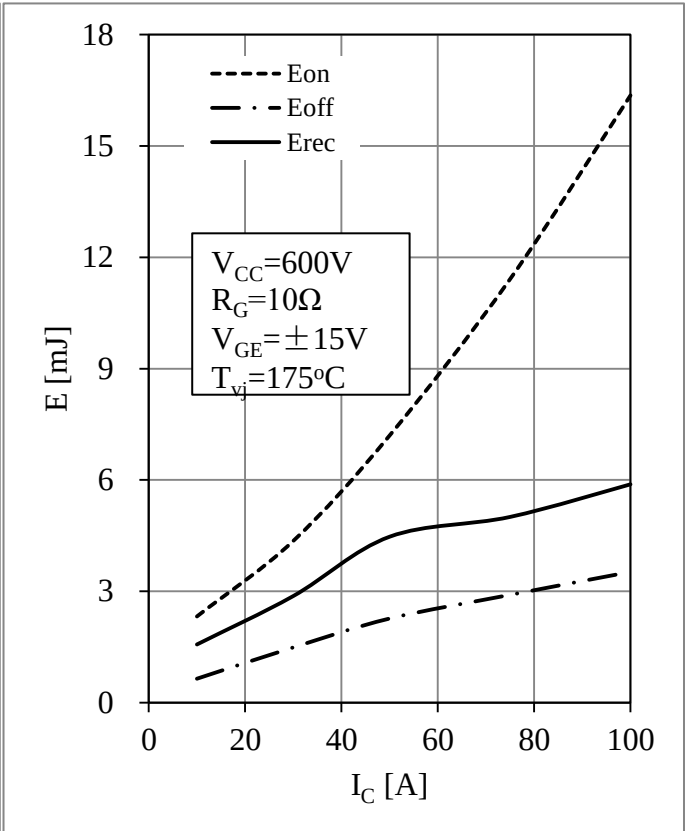
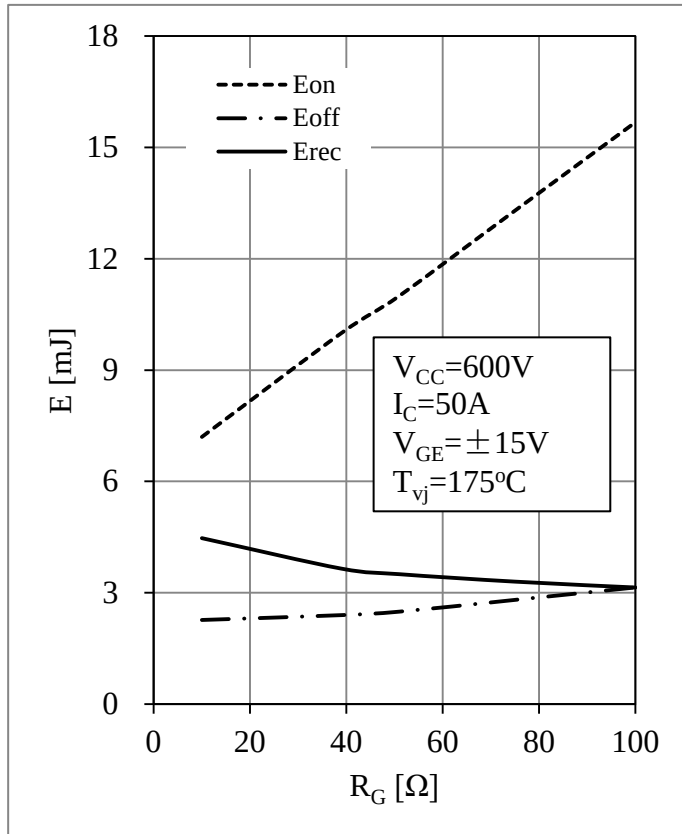
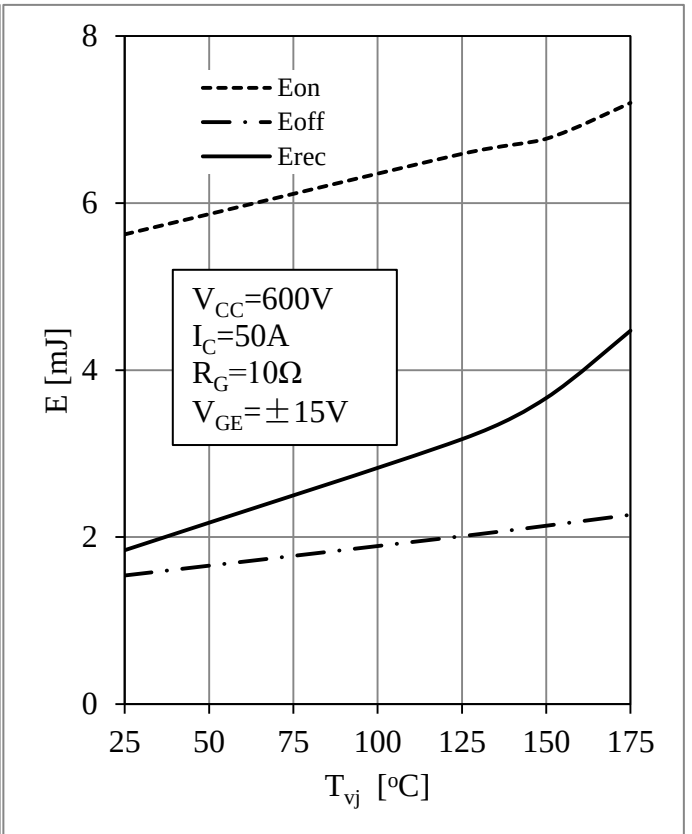
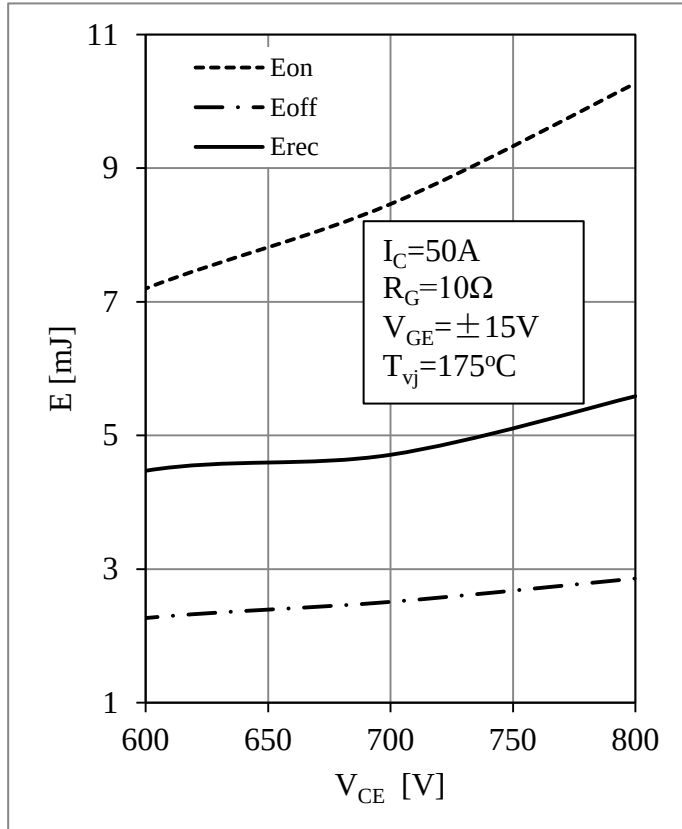
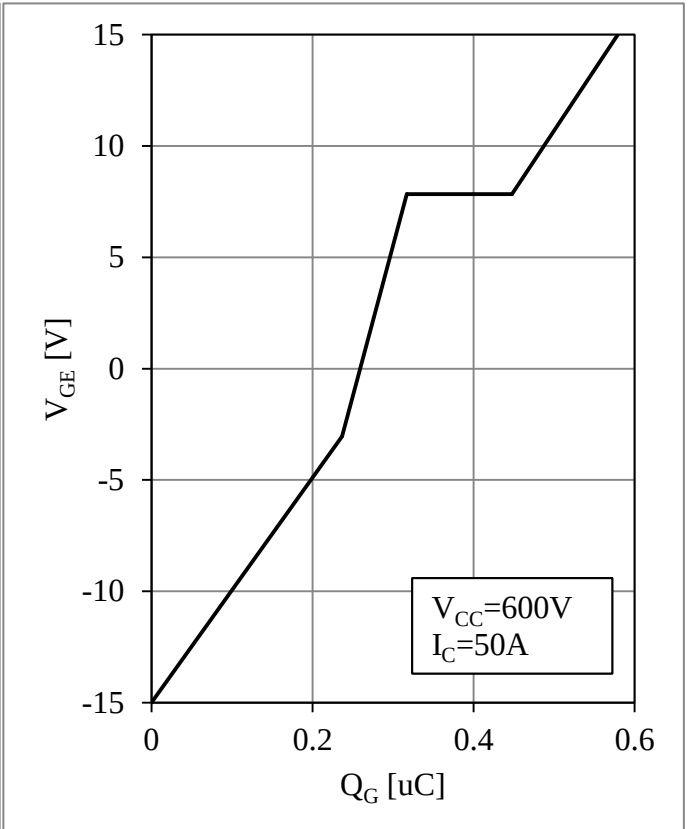
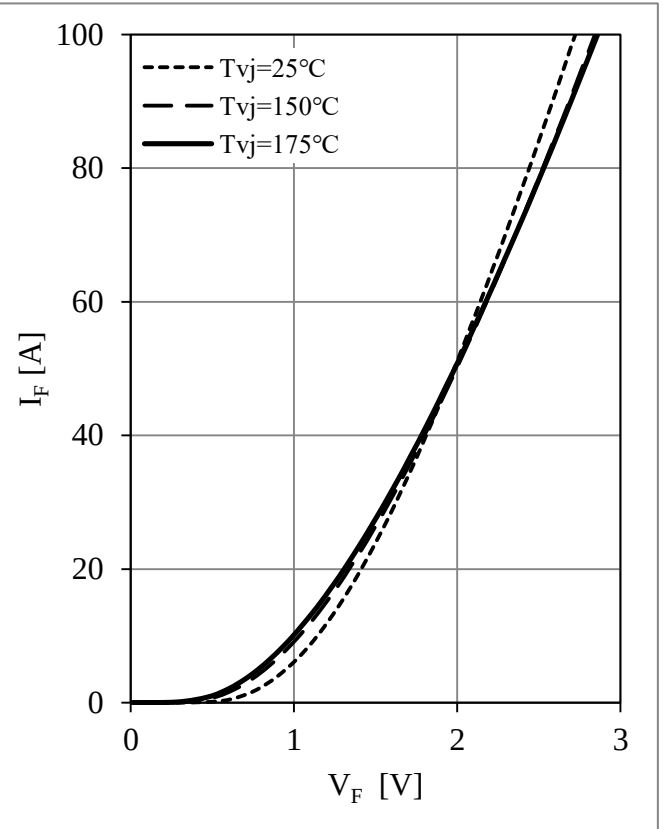
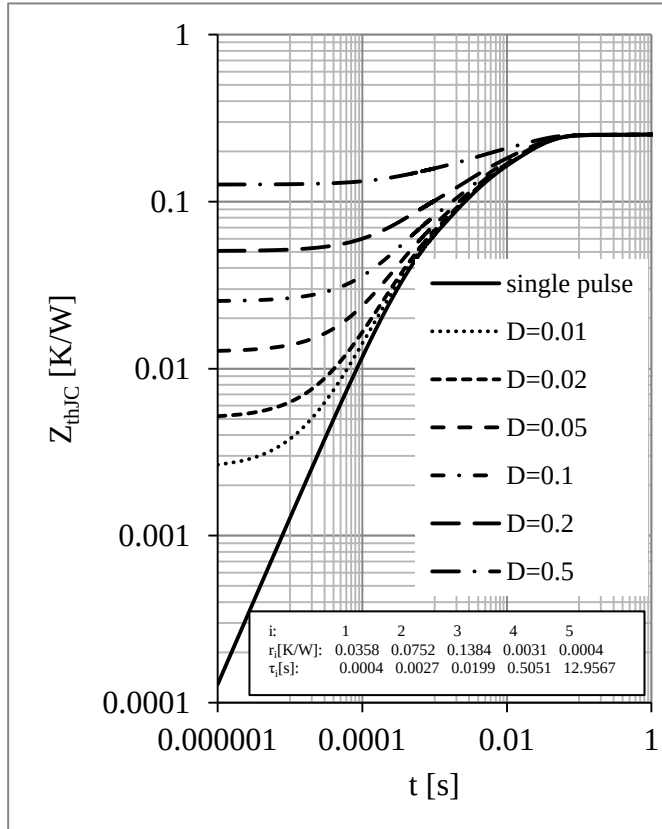
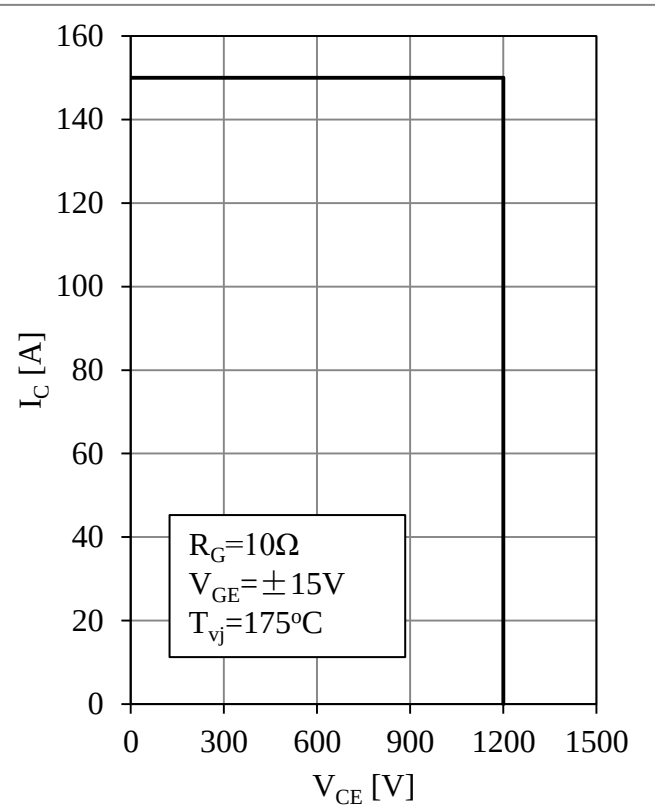
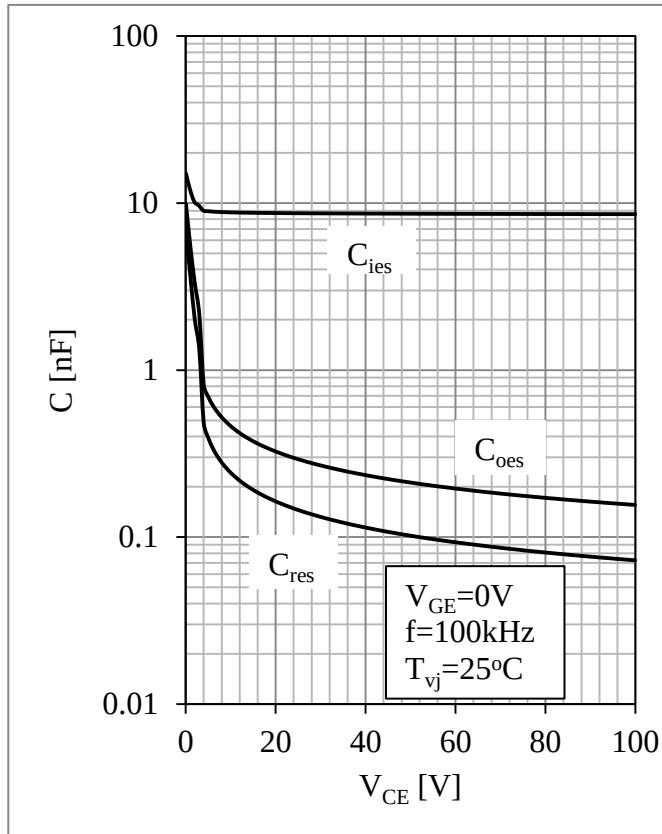
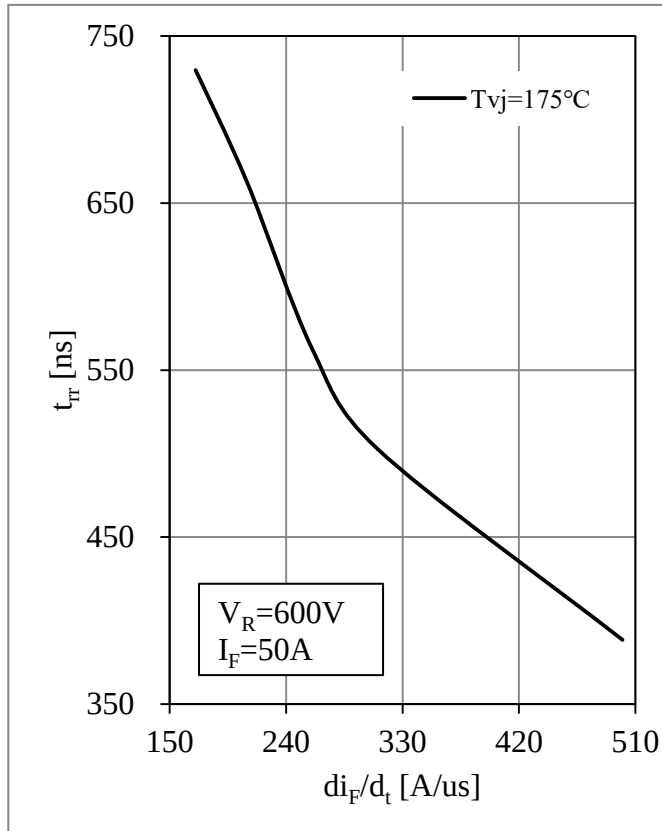
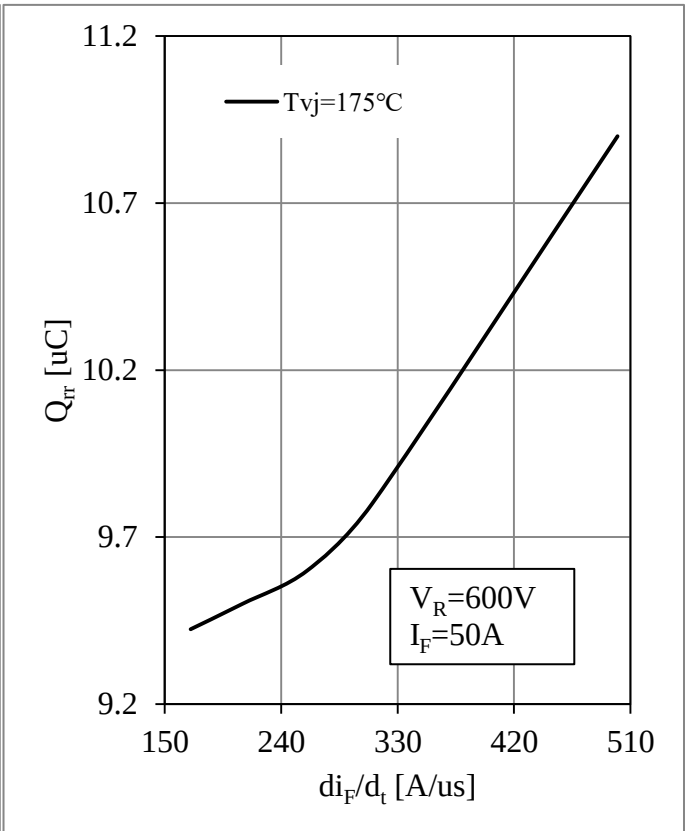
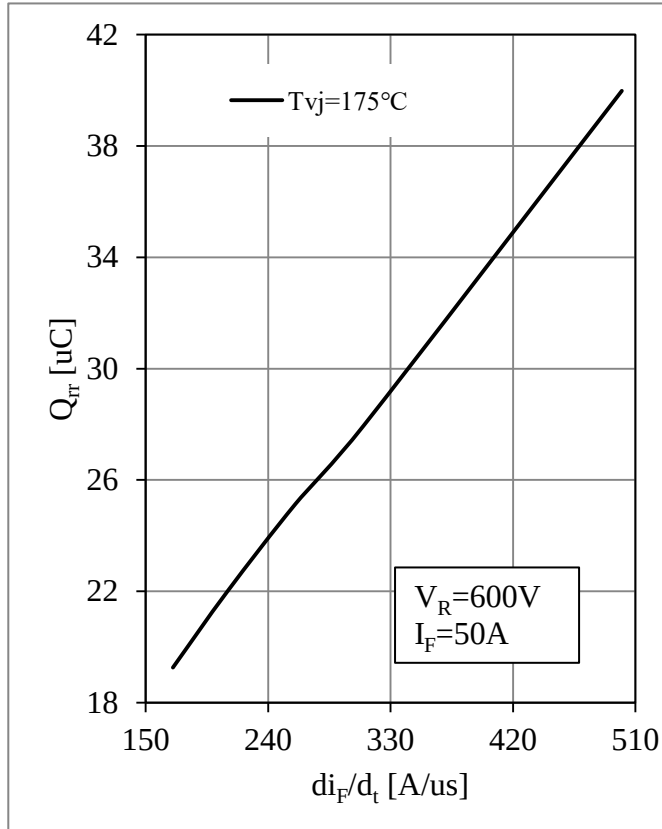
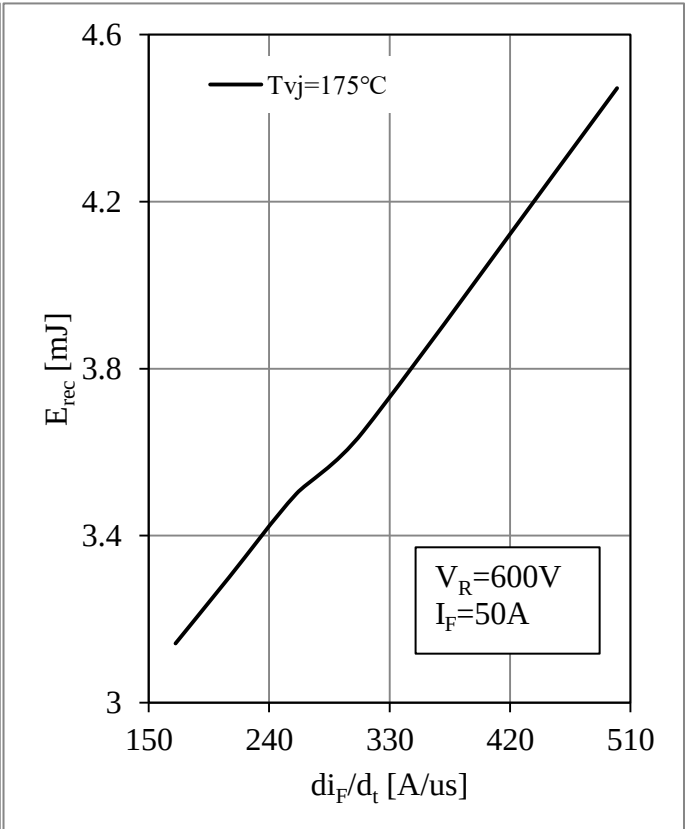


Fig 4. IGBT Transfer Characteristics

Fig 5. IGBT Switching Times as. I_C Fig 6. IGBT Switching Times as. R_G Fig 7. IGBT Switching Times vs. T_{vj} Fig 8. Switching Energy Loss vs. I_C

Fig 9. Switching Energy Loss vs. R_G Fig 10. Switching Energy Loss vs. T_{vj} Fig 11. Switching Energy Loss vs. V_{CE} Fig 12. IGBT Gate Charge vs. V_{GE}



Fig 17. Reverse Recovery Time vs. di_F/d_t Fig 18. Reverse Recovery Charge vs. di_F/d_t Fig 19. Reverse Recovery Current vs. di_F/d_t Fig 20. Reverse Energy Losses vs. di_F/d_t

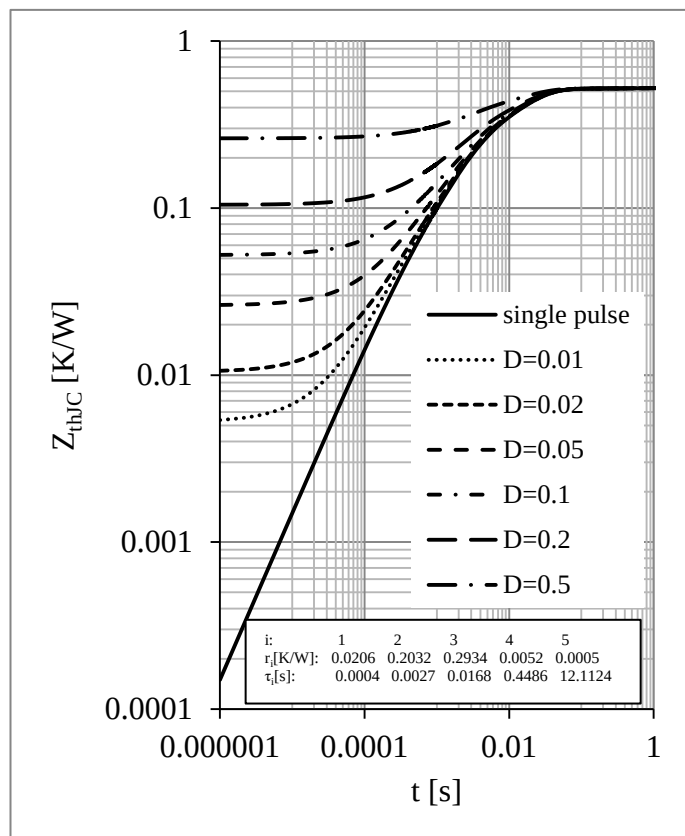
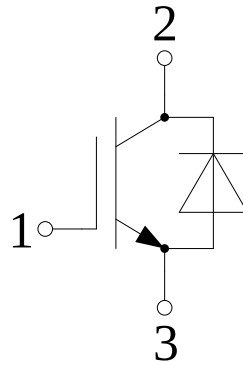


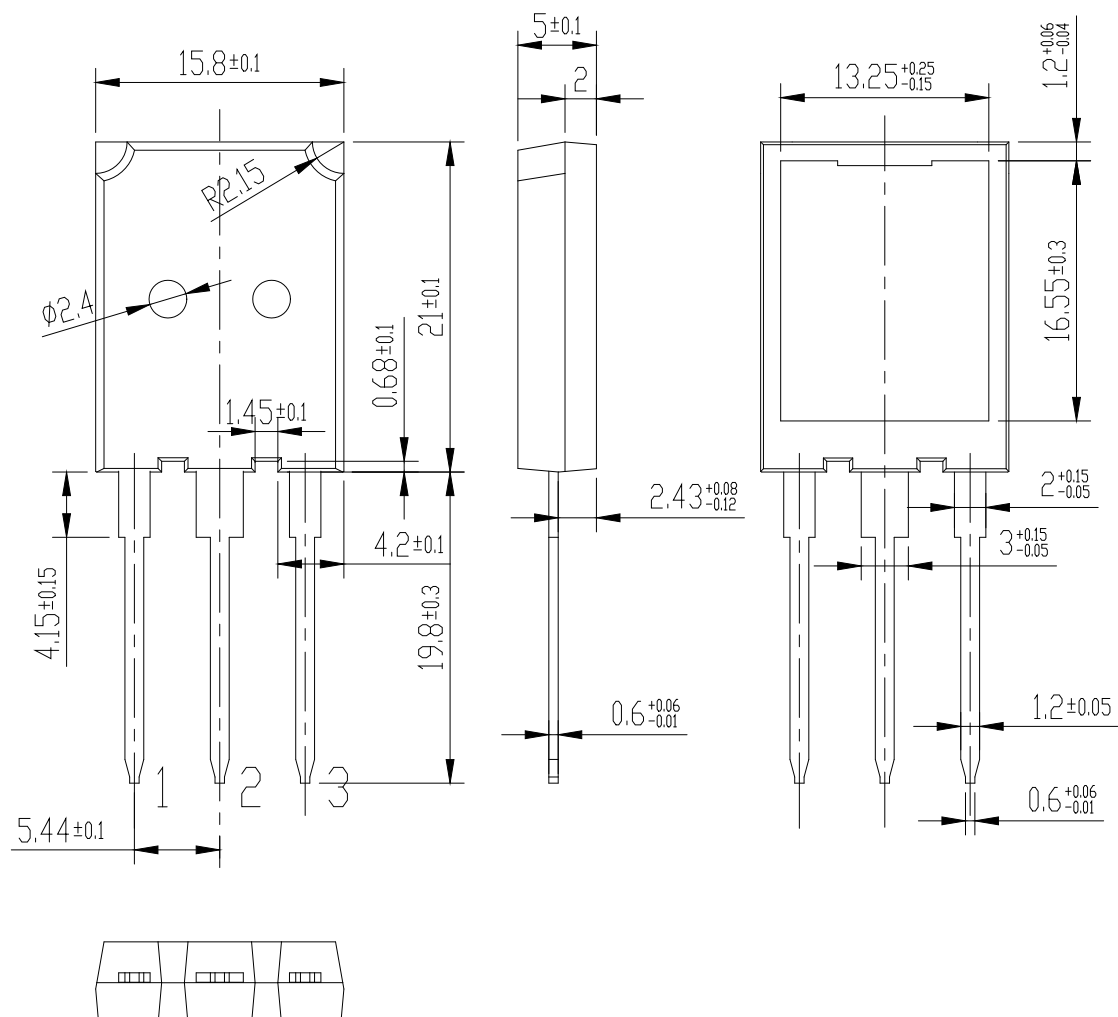
Fig 21. Diode Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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